

Single N-Channel Logic Level Enhancement Mode Field Effect Transistor

• Product Summary:

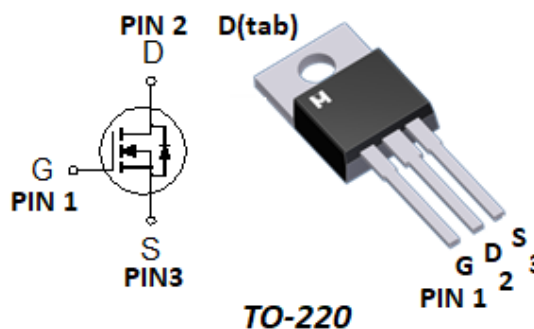
	N-CH
BVDSS	60 V
$R_{DS(on)} (MAX.) @ V_{GS}=10V$	3.5 mΩ
$I_D @ T_C=25^{\circ}C$	180 A

Single N Channel MOSFET

UIS, Rg 100% Tested

RoHS & Halogen Free & TSCA Compliant

• Pin Description:



• ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 30	V
Continuous Drain Current	$T_C = 25^{\circ}C$	I_D	180	A
	$T_C = 100^{\circ}C$		127	
Pulsed Drain Current ¹		I_{DM}	540	
Avalanche Current		I_{AS}	90	mJ
Avalanche Energy	$L = 0.1mH$	EAS	405	
Repetitive Avalanche Energy ²	$L = 0.05mH$	EAR	202.5	
Power Dissipation	$T_C = 25^{\circ}C$	P_D	277	W
	$T_C = 100^{\circ}C$		111	
Operating Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^{\circ}C$

• 100% UIS testing in condition of $V_D=30V$, $L=0.1mH$, $V_G=10V$, $I_L=60A$, Rated $V_{DS}=60V$ N-CH

• THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		0.45	$^{\circ}C/W$
Junction-to-Ambient ³	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

³The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}C$.

⁴Guarantee by Engineering test.



▪ ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250uA	60			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	2	3	4	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±30V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48V, V _{GS} = 0V			1	uA
		V _{DS} = 40V, V _{GS} = 0V, T _J = 125 °C			25	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = 10V, V _{GS} = 10V	180			A
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 10V, I _D = 50A		3.1	3.5	mΩ
Forward Transconductance ¹	g _{fs}	V _{DS} = 5V, I _D = 20A		60		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 30V, f = 1MHz		5519		pF
Output Capacitance	C _{oss}			815		
Reverse Transfer Capacitance	C _{rss}			50		
Gate Resistance	R _g	V _{GS} = 15mV, V _{DS} = 0V, f = 1MHz		1.7		Ω
Total Gate Charge ^{1,2}	Q _g (V _{GS} =10V)	V _{DS} = 30V, V _{GS} = 10V, I _D = 20A		61		nC
Gate-Source Charge ^{1,2}	Q _{gs}			36		
Gate-Drain Charge ^{1,2}	Q _{gd}			10		
Turn-On Delay Time ^{1,2}	t _{d(on)}	V _{DS} = 30V, V _{GS} = 10V, I _D = 20A , R _g = 6Ω		80		nS
Rise Time ^{1,2}	t _r			160		
Turn-Off Delay Time ^{1,2}	t _{d(off)}			100		
Fall Time ^{1,2}	t _f			180		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS						
Continuous Current	I _S				180	A
Pulsed Current ³	I _{SM}				540	
Forward Voltage ¹	V _{SD}	I _F = 50A, V _{GS} = 0V			1.3	V
Reverse Recovery Time	t _{rr}	I _F = 50A, dI _F /dt = 100A / uS		35		nS
Reverse Recovery Charge	Q _{rr}				270	

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

⁴Guarantee by FT test Item

⁵Guarantee by Engineering test

EMC will review datasheet by quarter, and update new version.



•TYPICAL CHARACTERISTICS

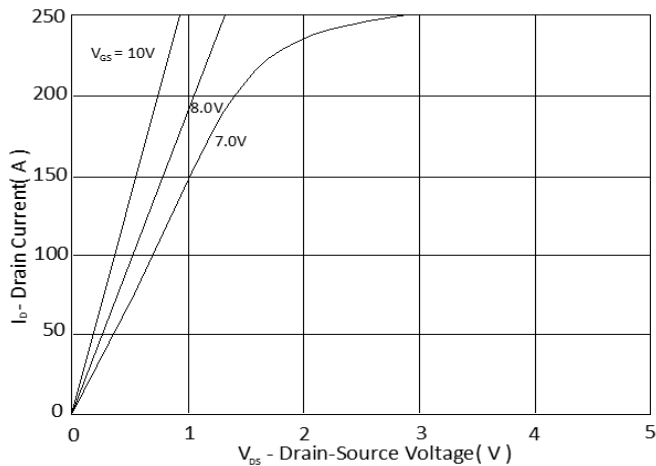


Fig.1 Typical Output Characteristics

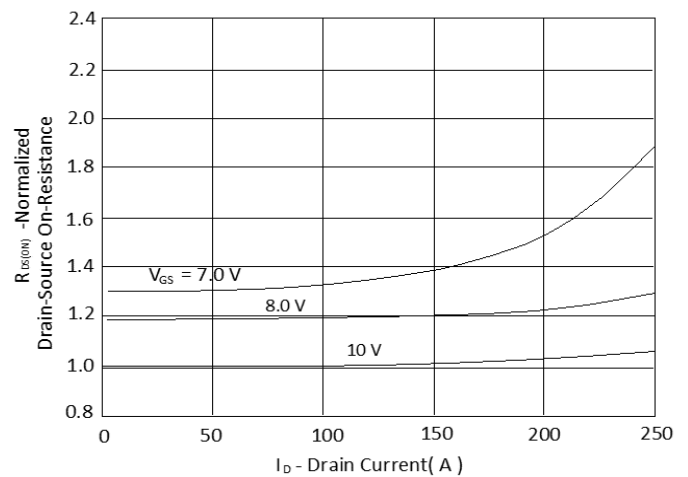


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

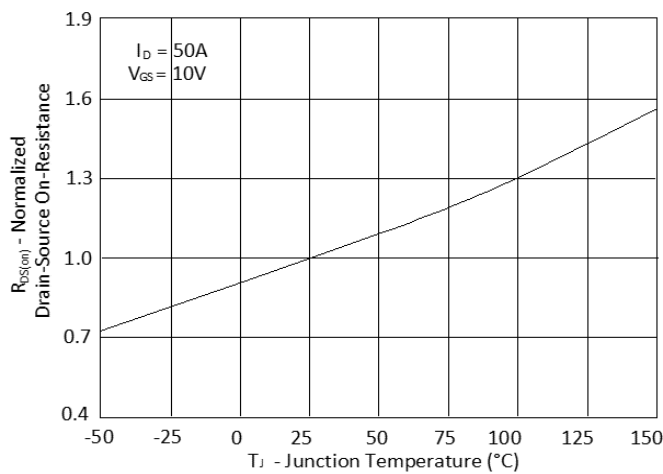


Fig.3 Normalized On-Resistance v.s. Junction Temperature

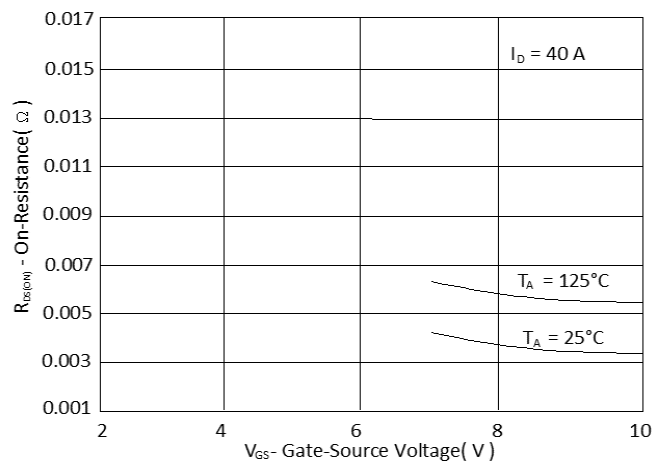


Fig.4 On-Resistance v.s. Gate Voltage

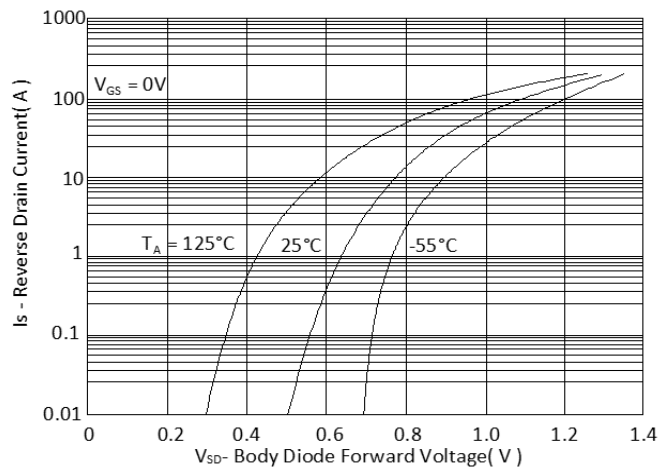


Fig.5 Forward Characteristic of Reverse Diode

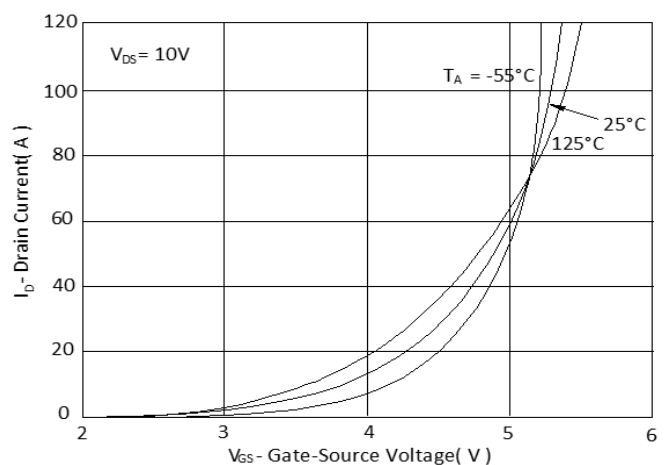


Fig.6 Transfer Characteristics

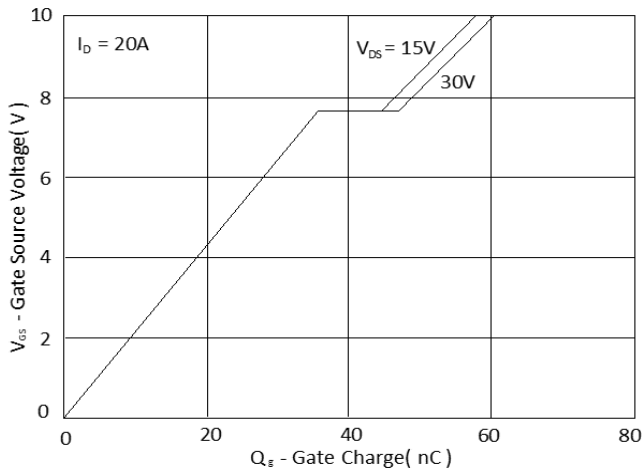


Fig.7 Gate Charge Characteristics

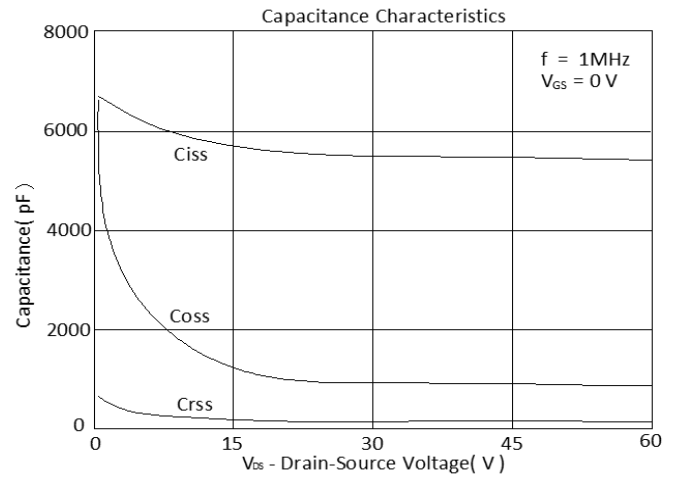


Fig.8 Typical Capacitance Characteristics

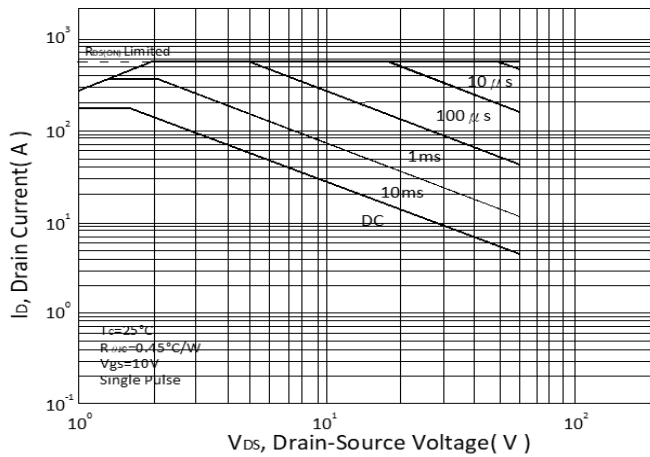


Fig.9. Maximum Safe Operating Area

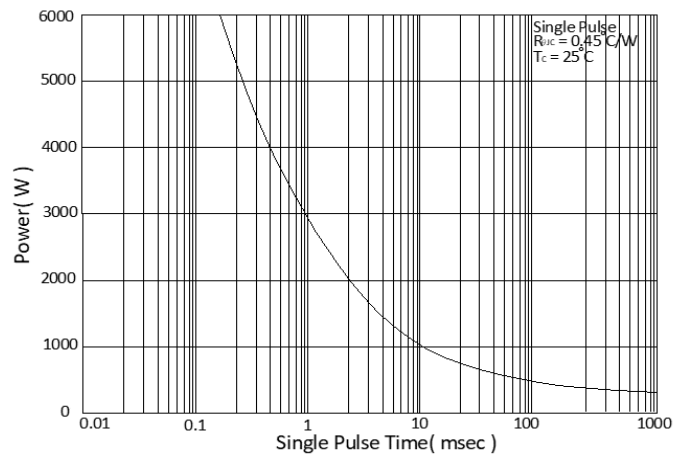


Fig.10. Single Pulse Maximum Power Dissipation

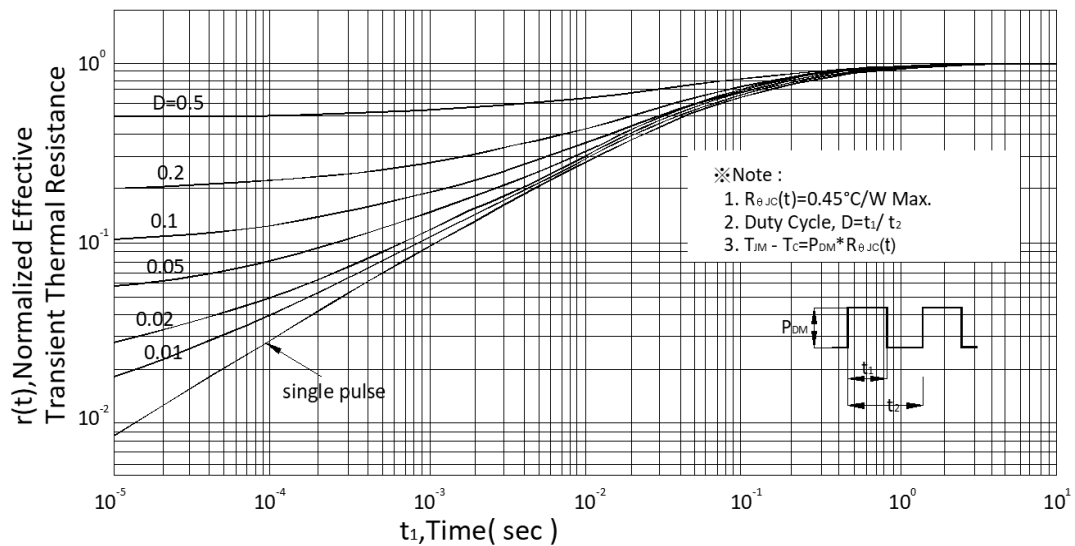
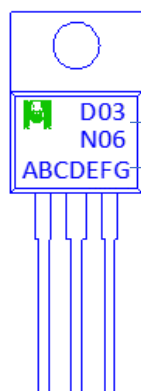


Fig.11. Effective Transient Thermal Impedance

Ordering & Marking Information:

Device Name: EMD03N06E for TO-220



D03N06: Device Name

ABCDEFGH: Date Code

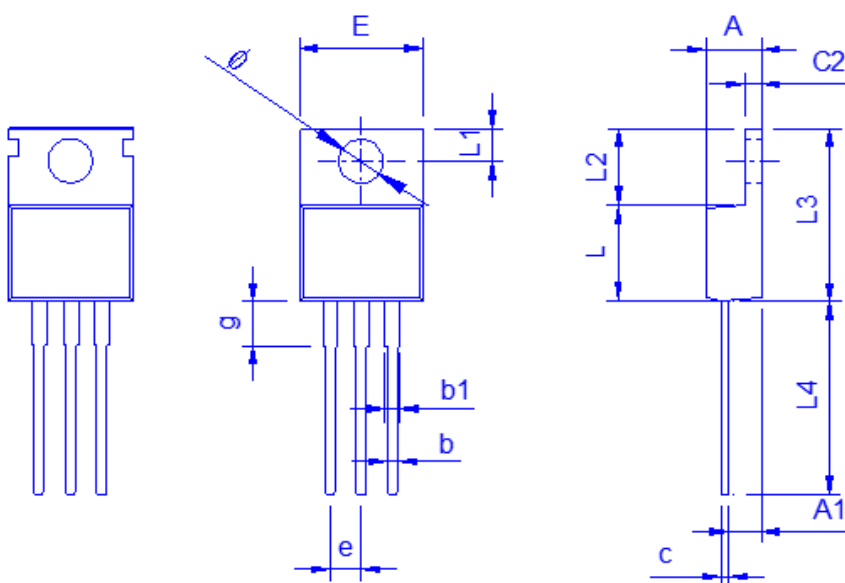
A: Assembly House

B: Year(A:2008 B:2009 C:2010....)

C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10 K:11 L:12)

DEFG: Serial No.

Outline Drawing



Dimension	A	A1	b	b1	c	c2	E	L	L1	L2	L3	L4	Ø
Min.	4.24	2.25	0.7	1.17	0.31	1.15	9.91	8.5	2.59	6.1	14.7	12.7	3.4
Typ.	4.44	2.4	0.8	1.55	0.5	1.27	10.16	8.92	2.8	6.3	15.37	13.72	3.84
Max.	4.7	2.82	0.91	1.75	0.65	1.4	10.36	9.75	3.25	6.8	16.9	13.97	3.935

Dimension	e	g
Min.	2.44	2.85
Typ.	2.54	3.8
Max.	2.64	4

◆ **Tape&Reel Information: 50pcs/Tube (1000pcs/Box)**

